

Product Change Notification

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Product Change Notification Number: GC191443

Date 29 April 2019

Title: Encapsulation process change on the TBGA package variants of PC8245/8260/8265 product family

Product Identification:

PC8245MTPU300D	PC8245MTPU350D	PC8260AMTPUMHBBZG2
PC8245MTPU333D	PC8260AMTPUMHBB	PC8265AMTPUMHBC

See also https://www.teledyne-e2v.com/shared/content/resources/File/documents/Semiconductors/PCN_EOLs/GE184051_EOL.pdf

Reason for Change:

- | | | | |
|--|---|---|--|
| <input type="checkbox"/> Logistics | <input type="checkbox"/> Design | <input type="checkbox"/> wafer Processing | <input type="checkbox"/> wafer Materials |
| <input checked="" type="checkbox"/> Process Material | <input type="checkbox"/> Other | <input type="checkbox"/> Manufacturing Location | <input type="checkbox"/> Quality/Reliability |
| | <input checked="" type="checkbox"/> Assembly Material | <input type="checkbox"/> Product Marking | |

Change Description:

Teledyne e2v aligns with NXP announcement ref. 201803021F01.

- TBGA Package encapsulation process change from Glob Top to Center Gate Mold.

Anticipated Impact of Product Change (Form, Fit, Function):

No changes will be seen in form, fit, or function. No impact to existing datasheet

Identification Method to Distinguish Change:

None. Product identification does not change.

Qualification Data:

- | | | |
|---|--|--|
| <input type="checkbox"/> available | <input checked="" type="checkbox"/> will be available in November-2019 | <input checked="" type="checkbox"/> not applicable |
| <input type="checkbox"/> prototypes available | <input type="checkbox"/> will be available | <input checked="" type="checkbox"/> not applicable |

Quantifiable Impact on Quality & Reliability: *None expected.*

Implementation Date*: Estimated end of November-2019

**The Estimated Implementation Date is the forecasted date that a customer may expect to receive changed product. This is determined by the estimated date of inventory depletion on the PCN issue date. This may be affected by fluctuations in supply and demand. Consequently, although customers should be prepared to receive changed product on this date, e2v semiconductors will continue to ship pre-changed product until a time in which inventory has been depleted. This may result in pre-changed product being shipped to customers after this forecasted date.*

Teledyne e2v semiconductors contact:

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Please contact your local Teledyne-e2v sales representative for any commercial inquiry.

APPROVAL by TRB

Teledyne e2v semiconductors will deem this change accepted unless specific conditions of acceptance are provided in writing within 30 days from the date of this notice. All correspondence must be sent to the contact e-mail addresses indicated above.

A Teledyne e2v semiconductor assumes no responsibility for any errors that may appear in this document.

The supply of products will be subject to Teledyne e2v general terms and conditions of sale or any specific contractual terms agreed between the parties.

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